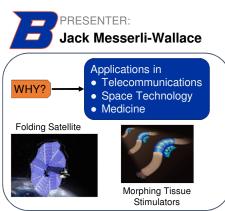
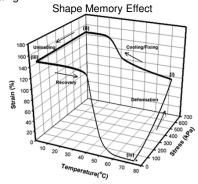
Title: All-Printed Morphing **Electronics**



INTRODUCTION

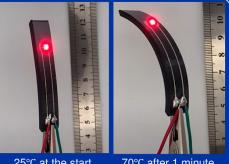
Shape Memory Polymers (SMPs): Polymers that have a memorized shape in which they return to after deformation and subsequent heating.



Objective: Use Hyrel Multi-head 3D printing to fabricate a SMP and an activating conductive paste in one print.

- Polylactic acid (PLA) and thermoplastic polyurethane (TPU) are low cost, common 3D-printing polymers.
- A PLA/TPU mix has a strong shape memory effect and adequate rigidity.
- Conductive paste is printed directly on the SMP via syringe deposition.
- Electricity is sent through the cured paste, generating heat to activate the shape memory effect.
- A carbon-based paste (Dupont 7082) and a silver-based paste (Dupont 5029) have been tested.

We have fabricated morphing electronics through shape memory polymers and conductive paste heating.



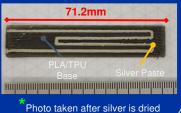
25°C at the start

70°C after 1 minute

Scan to see the sample being printed!



Open Silver Sample in Permanent Form



Takeaways

Print Speed

(mm/s)

15

30

Carbon Paste Printing Results:

Extrusion

Multiplier

(1=100%)

1.0

0.6

Carbon paste resistivity is always too high for low-current applications, but

could be used for sunlight activation.

Resistivity

 $(k\Omega)$

71.05

151.2

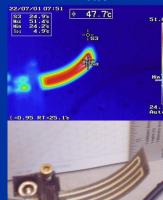
242.4

- Silver Paste Printing Results: • Printed at 10mm/s, 1.0 extrusion multiplier
- Resistance of circuit is about 1Ω, suitable for the application.
- Open silver-SMP samples exhibit SMP effect under 1.2-2.0 amps.
- · Open circuit continuity breaks as the sample straightens.
- Closed silver-SMP samples exhibit SMP effect under 1.0-1.6 amps.
- Closed circuit continuity has not been broken over three testing cycles.

Testing:

Fabrication:

Open sample heated with 1.6 amps for three minutes

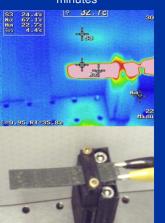


Closed sample heated with 1.2 amps for three minutes

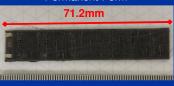
Bend into

emporary

70°C



Closed Silver Sample in Permanent Form



Silver Paste is encapsulated in the PLA/TPU SMP

- Improves thermal isolation Lowers required current
- · Prevents silver from cracking

Scan to see the sample transform!



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Acknowledgements

The project described was supported by the National Science Foundation via the Research Experience for Undergraduates Site: Materials for Society (Award No. 1950305) and by the Micron School of Materials Science & Engineering at Boise State University.